



NOTES:

1. REFERENCE
2. EQUIVALENT TO KYOCERA DWG NO. KD-S92129
3. PLATING THICKNESS TO BE MINIMUM 60 MICROINCHES GOLD OVER 50-350 MICROINCHES NICKEL.
4. SEAL AREA TO BE METALLIZED.
5. DIE ATTACH AREA TO BE METALLIZED.
6. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
7. LEAD RESISTANCE: 0.4Ω MAX.
8. CERAMIC BODY ENDS SHALL BE CHAMFERED TO REDUCE CHIPPING AND ELIMINATE CRACKING.

Controlling Units millimeters <input type="checkbox"/> inches <input checked="" type="checkbox"/>	ABC0	4-4-92
	Drawn BWJ	Date
	Check <i>[Signature]</i>	Date
	Approved _____	Date _____
.X=±.1 .XX=±.02 .XXX=±.002 .XXXX=±.0002 Angles=±2°		32 LEAD SIDE
Approved _____		KD-S92129

CSB03216



